



## DISCRIPTION

### FEATURES

Ceramic Core  
 High frequency design  
 Excellent Q values  
 Excellent SRF  
 High reliability  
 Excellent thermal stability

### OPTIONS

Tape & Reel is Standard ( Qty: 3.000 Pcs )  
 Bulk Packing Available for smaller quantities  
 Tolerance: J = 5% and K=10% is Standard,  
 tighter Tolerance available ( MOQ on request )

### APPLICATIONS

Modems  
 Mobile Radios  
 Cordless Telephones  
 Global Positioning Systems  
 Telecommunications Systems

## PHYSICAL CHARACTERISTICS

- Testing : ( Equivalents acceptable ) Inductance & Q-HP4191A + HP4291A  
 SRF : HP8553B ; RDC : 25°C
- Operating Temperature : Ceramic -55°C ~ 125°C
- Pad metalization : Tungsten-nickel with gold flash
- Solder methods : Wave, Reflow, Vapor Phase
- Solderability : Max 260°C for 10 seconds
- Marking : EIA color code

## ELECTRICAL SPECIFICATIONS

Properties	Test conditions		Value	Unit	Tol.
Inductance		<b>L</b>	3,9	nH	see Site 2
Q factor		<b>Q</b>	30		min.
DC-resistance		<b>DCR typ.</b>	---	Ω	typ.
DC-resistance		<b>DCR max.</b>	0,050	Ω	max.
Self-Res. Freq.		<b>SRF</b>	6000	Mhz	min.
Test-Freq.			1500	Mhz	
Rated Current		<b>IDC</b>	1000	mA	max.
Saturation Current		<b>Isat</b>	---	mA	typ.

1. This electronic component is meant to be used in general electronic equipment. Before the incorporation of this component into any equipment with higher and more reliable requirements such as aviation, aerospace, submarine, nuclear control, transportation, transportation signal, disaster prevention, medical, public information network, etc. or if there is a possibility of injuries or damages to the human body, Edcon -Components must be informed before the stage of design-in. Evaluation checks for safety have to be performed on each electronic components used in electrical circuits that require high safety and reliability functions.

### SMT WIRE-WOUND CERAMIC CHIP INDUCTORS

Part No.: **S12005-3N9**

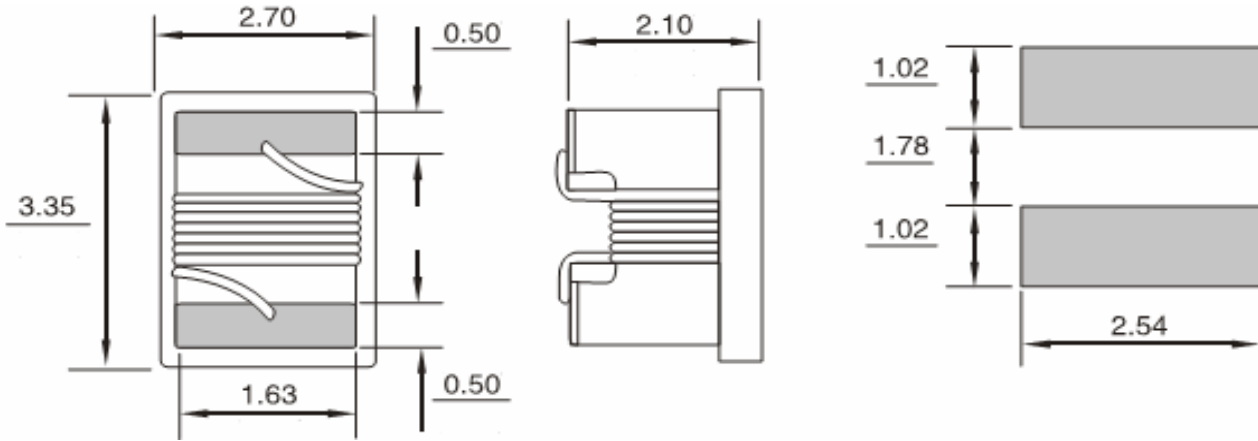
Customer:

DRW:	Chang	CHKD	Young	MATL:	Chu Chi	DATE	09.06.2009
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**TECHNICAL INFORMATIONS**

**Dimensions ( mm )**

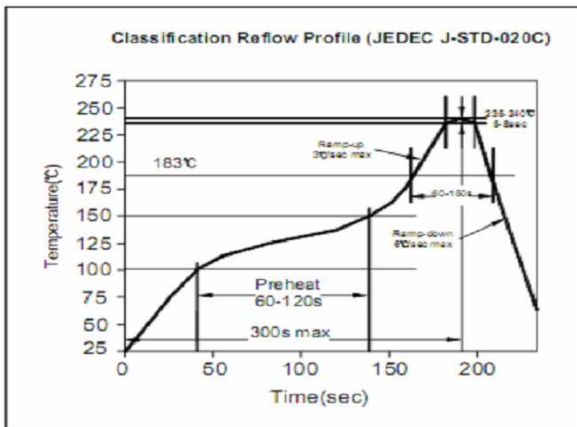


**Ordering Information**

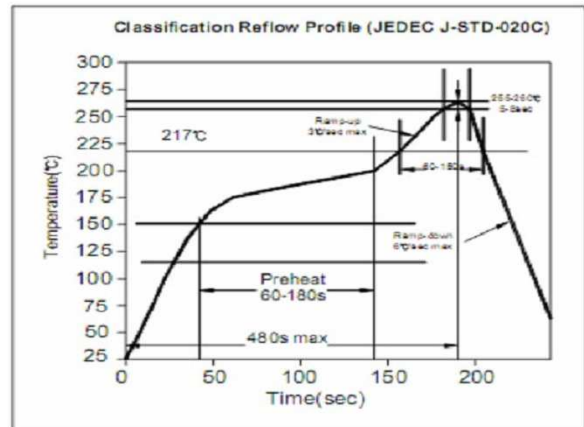
Serie and Range
S12005-3N9

Tolerance	ROHS	Packing
K	R	TR
J = 5%	R = ROHS	BU = Bulk Ware
K = 10%	N = non ROHS	TR = Tape Reel
M = 20%		
N = 30%		

**Soldering Profile for Lead Free Soldering  
 235-240°C**



**Soldering Profile for Lead Free Soldering  
 255-260°C**



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